

L Number	Hits	Search Text	DB	Time stamp
1	5	scrubber with grounded	USPAT	2004/01/14 13:45
2	96	scrubber with ground not (scrubber with grounded)	USPAT	2004/01/14 13:35
3	21	(scrubber with ground not (scrubber with grounded)) and flue with gas	USPAT	2004/01/14 13:34
4	21	(scrubber with ground not (scrubber with grounded)) and (flue with gas)	USPAT	2004/01/14 13:35
5	96	(scrubber with ground) not (scrubber with grounded)	USPAT	2004/01/14 13:35
6	21	((scrubber with ground) not (scrubber with grounded)) and (flue with gas)	USPAT	2004/01/14 13:35
7	6	scrubber with grounded	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 13:50
8	0	grounded adj1 scrubber	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 13:50
9	20	grounded same scrubber	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 13:54
10	22	grounded with (flue and gas)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 13:57
11	5	grounded with (flue and gases)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 13:58
12	24	grounded with (exhaust and gases)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 14:00
13	313	grounded with exhaust	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 14:00
15	3	((grounded with exhaust) not (grounded with (exhaust and gases))) and abatement	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 14:01
14	289	(grounded with exhaust) not (grounded with (exhaust and gases))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 14:05
16	3	((grounded with exhaust) not (grounded with (exhaust and gases))) and (nozzles with spray\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 14:02
17	9	scrubber.ti. and grounded	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 14:06

-	8748	118/715.ccls. or 118/728.ccls. or 118/50.ccls. or 156/345.29.ccls. or 156/345.33.ccls. or 156/345.34.ccls. or 156/345.35.ccls. or 156/345.36.ccls. or 156/345.26.ccls. or 156/345.51.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 09:36
-	8045	137/262-264.ccls. or 137/454.2 or 137/560.ccls. or 137/561r.ccls. or 137/561a.ccls. or 137/571-576.ccls. or 137/590.ccls. or 137/594-596.ccls. or 137/599.01.ccls. or 137/599.05-599.07.ccls. or 137/602.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 09:36
-	2288	141/285-286.ccls. or 141/37.ccls. or 141/44-47.ccls. or 141/54.ccls. or 141/301-302.ccls. or 141/367.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 09:36
-	457	261/127.ccls. or 261/131.ccls. or 261/146-147.ccls. or 261/150.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 09:36
-	2576	261/19-22.ccls. or 261/23.1.ccls. or 261/40.ccls. or 261/42.ccls. or 261/62-63.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 09:36
-	7032	261/64.1.ccls. or 261/65.ccls. or 261/75-76.ccls. or 261/94-96.ccls. or 261/100-102.ccls. or 261/105.ccls. or 261/108-109.ccls. or 261/113.ccls. or 261/114.1.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 09:36
-	28494	(118/715.ccls. or 118/728.ccls. or 118/50.ccls. or 156/345.29.ccls. or 156/345.33.ccls. or 156/345.34.ccls. or 156/345.35.ccls. or 156/345.36.ccls. or 156/345.26.ccls. or 156/345.51.ccls.) or (137/262-264.ccls. or 137/454.2 or 137/560.ccls. or 137/561r.ccls. or 137/561a.ccls. or 137/571-576.ccls. or 137/590.ccls. or 137/594-596.ccls. or 137/599.01.ccls. or 137/599.05-599.07.ccls. or 137/602.ccls.) or (141/285-286.ccls. or 141/37.ccls. or 141/44-47.ccls. or 141/54.ccls. or 141/301-302.ccls. or 141/367.ccls.) or (261/127.ccls. or 261/131.ccls. or 261/146-147.ccls. or 261/150.ccls.) or (261/19-22.ccls. or 261/23.1.ccls. or 261/40.ccls. or 261/42.ccls. or 261/62-63.ccls.) or (261/64.1.ccls. or 261/65.ccls. or 261/75-76.ccls. or 261/94-96.ccls. or 261/100-102.ccls. or 261/105.ccls. or 261/108-109.ccls. or 261/113.ccls. or 261/114.1.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 09:36
-	2	us-20020136671-\$ did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 09:58
-	57	((effluent or flue) with (gas and treatment)) and ((118/715.ccls. or 118/728.ccls. or 118/50.ccls. or 156/345.29.ccls. or 156/345.33.ccls. or 156/345.34.ccls. or 156/345.35.ccls. or 156/345.36.ccls. or 156/345.26.ccls. or 156/345.51.ccls.) or (137/262-264.ccls. or 137/454.2 or 137/560.ccls. or 137/561r.ccls. or 137/561a.ccls. or 137/571-576.ccls. or 137/590.ccls. or 137/594-596.ccls. or 137/599.01.ccls. or 137/599.05-599.07.ccls. or 137/602.ccls.) or (141/285-286.ccls. or 141/37.ccls. or 141/44-47.ccls. or 141/54.ccls. or 141/301-302.ccls. or 141/367.ccls.) or (261/127.ccls. or 261/131.ccls. or 261/146-147.ccls. or 261/150.ccls.) or (261/19-22.ccls. or 261/23.1.ccls. or 261/40.ccls. or 261/42.ccls. or 261/62-63.ccls.) or (261/64.1.ccls. or 261/65.ccls. or 261/75-76.ccls. or 261/94-96.ccls. or 261/100-102.ccls. or 261/105.ccls. or 261/108-109.ccls. or 261/113.ccls. or 261/114.1.ccls.))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 10:06

	16	((effluent or flue) with (gas and treatment)) and ((118/715.ccls. or 118/728.ccls. or 118/50.ccls. or 156/345.29.ccls. or 156/345.33.ccls. or 156/345.34.ccls. or 156/345.35.ccls. or 156/345.36.ccls. or 156/345.26.ccls. or 156/345.51.ccls.) or (137/262-264.ccls. or 137/454.2 or 137/560.ccls. or 137/561r.ccls. or 137/561a.ccls. or 137/571-576.ccls. or 137/590.ccls. or 137/594-596.ccls. or 137/599.01.ccls. or 137/599.05-599.07.ccls. or 137/602.ccls.) or (141/285-286.ccls. or 141/37.ccls. or 141/44-47.ccls. or 141/54.ccls. or 141/301-302.ccls. or 141/367.ccls.) or (261/127.ccls. or 261/131.ccls. or 261/146-147.ccls. or 261/150.ccls.) or (261/19-22.ccls. or 261/23.1.ccls. or 261/40.ccls. or 261/42.ccls. or 261/62-63.ccls.) or (261/64.1.ccls. or 261/65.ccls. or 261/75-76.ccls. or 261/94-96.ccls. or 261/100-102.ccls. or 261/105.ccls. or 261/108-109.ccls. or 261/113.ccls. or 261/114.1.ccls.))) and (steel or resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 10:07
	74	((effluent or flue) same (gas and treatment)) and ((118/715.ccls. or 118/728.ccls. or 118/50.ccls. or 156/345.29.ccls. or 156/345.33.ccls. or 156/345.34.ccls. or 156/345.35.ccls. or 156/345.36.ccls. or 156/345.26.ccls. or 156/345.51.ccls.) or (137/262-264.ccls. or 137/454.2 or 137/560.ccls. or 137/561r.ccls. or 137/561a.ccls. or 137/571-576.ccls. or 137/590.ccls. or 137/594-596.ccls. or 137/599.01.ccls. or 137/599.05-599.07.ccls. or 137/602.ccls.) or (141/285-286.ccls. or 141/37.ccls. or 141/44-47.ccls. or 141/54.ccls. or 141/301-302.ccls. or 141/367.ccls.) or (261/127.ccls. or 261/131.ccls. or 261/146-147.ccls. or 261/150.ccls.) or (261/19-22.ccls. or 261/23.1.ccls. or 261/40.ccls. or 261/42.ccls. or 261/62-63.ccls.) or (261/64.1.ccls. or 261/65.ccls. or 261/75-76.ccls. or 261/94-96.ccls. or 261/100-102.ccls. or 261/105.ccls. or 261/108-109.ccls. or 261/113.ccls. or 261/114.1.ccls.)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 10:08
	3	((effluent or flue) same (gas and treatment)) and ((118/715.ccls. or 118/728.ccls. or 118/50.ccls. or 156/345.29.ccls. or 156/345.33.ccls. or 156/345.34.ccls. or 156/345.35.ccls. or 156/345.36.ccls. or 156/345.26.ccls. or 156/345.51.ccls.) or (137/262-264.ccls. or 137/454.2 or 137/560.ccls. or 137/561r.ccls. or 137/561a.ccls. or 137/571-576.ccls. or 137/590.ccls. or 137/594-596.ccls. or 137/599.01.ccls. or 137/599.05-599.07.ccls. or 137/602.ccls.) or (141/285-286.ccls. or 141/37.ccls. or 141/44-47.ccls. or 141/54.ccls. or 141/301-302.ccls. or 141/367.ccls.) or (261/127.ccls. or 261/131.ccls. or 261/146-147.ccls. or 261/150.ccls.) or (261/19-22.ccls. or 261/23.1.ccls. or 261/40.ccls. or 261/42.ccls. or 261/62-63.ccls.) or (261/64.1.ccls. or 261/65.ccls. or 261/75-76.ccls. or 261/94-96.ccls. or 261/100-102.ccls. or 261/105.ccls. or 261/108-109.ccls. or 261/113.ccls. or 261/114.1.ccls.))) and (steel or resin) not (((effluent or flue) with (gas and treatment)) and ((118/715.ccls. or 118/728.ccls. or 118/50.ccls. or 156/345.29.ccls. or 156/345.33.ccls. or 156/345.34.ccls. or 156/345.35.ccls. or 156/345.36.ccls. or 156/345.26.ccls. or 156/345.51.ccls.) or (137/262-264.ccls. or 137/454.2 or 137/560.ccls. or 137/561r.ccls. or 137/561a.ccls. or 137/571-576.ccls. or 137/590.ccls. or 137/594-596.ccls. or 137/599.01.ccls. or 137/599.05-599.07.ccls. or 137/602.ccls.) or (141/285-286.ccls. or 141/37.ccls. or 141/44-47.ccls. or 141/54.ccls. or 141/301-302.ccls. or 141/367.ccls.) or (261/127.ccls. or 261/131.ccls. or 261/146-147.ccls. or 261/150.ccls.) or (261/19-22.ccls. or 261/23.1.ccls. or 261/40.ccls. or 261/42.ccls. or 261/62-63.ccls.) or (261/64.1.ccls. or 261/65.ccls. or 261/75-76.ccls. or 261/94-96.ccls. or 261/100-102.ccls. or 261/105.ccls. or 261/108-109.ccls. or 261/113.ccls. or 261/114.1.ccls.))) and (steel or resin))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 10:07
	6	((effluent or flue) same ((gas with treatment) and steel)) and (CVD or "vapor deposition" or "vapour deposition")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 10:28
	6	((effluent or flue) same ((gas with treatment) and steel)) and (CVD or "vapor deposition" or "vapour deposition")) and steel	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 10:29

-	0	(((((effluent or flue) same ((gas with treatment) and steel)) and (CVD or "vapor deposition" or "vapour deposition")) and steel) and (ground\$3 or earth\$2))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 10:29
-	109	((effluent or flue) and ((gas with treatment) and steel)) and (CVD or "vapor deposition" or "vapour deposition")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 10:30
-	109	(((((effluent or flue) and ((gas with treatment) and steel)) and (CVD or "vapor deposition" or "vapour deposition")) and steel	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 10:30
-	0	(((((effluent or flue) same ((gas with treatment) and steel)) and (CVD or "vapor deposition" or "vapour deposition")) and steel) and (ground\$3 or earth\$2)) and (ground\$3 or earth\$2))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 10:30
-	171	((effluent or flue) and ((gas with treat\$4) and steel)) and (CVD or "vapor deposition" or "vapour deposition")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 10:48
-	171	(((((effluent or flue) and ((gas with treat\$4) and steel)) and (CVD or "vapor deposition" or "vapour deposition")) and steel	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 10:52
-	76	(((((effluent or flue) and ((gas with treat\$4) and steel)) and (CVD or "vapor deposition" or "vapour deposition")) and steel) and (ground\$3 or earth\$2))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 10:42
-	52	(((((effluent or flue) and ((gas with treat\$4) and steel)) and (CVD or "vapor deposition" or "vapour deposition")) and steel) and (grounded or ground or earthed))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 10:52
-	1090	((effluent or flue) and ((gas with treat\$4) and steel)) and (wafer or substrate or semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 11:10
-	1090	(((((effluent or flue) and ((gas with treat\$4) and steel)) and (wafer or substrate or semiconductor)) and steel	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 10:52
-	30	(((((effluent or flue) and ((gas with treat\$4) and steel)) and (wafer or substrate or semiconductor)) and steel) and ((grounded or ground or earthed) with steel)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 10:52
-	21	(((((effluent or flue) and ((gas with treat\$4) and steel)) and (wafer or substrate or semiconductor)) and steel) and ((grounded or ground or earthed) with steel)) not ((((((effluent or flue) and ((gas with treat\$4) and steel)) and (CVD or "vapor deposition" or "vapour deposition")) and steel) and ((grounded or ground or earthed))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 10:55
-	1069	(((((effluent or flue) and ((gas with treat\$4) and steel)) and (wafer or substrate or semiconductor)) and steel) not ((((((effluent or flue) and ((gas with treat\$4) and steel)) and (wafer or substrate or semiconductor)) and steel) and ((grounded or ground or earthed) with steel)) not ((((((effluent or flue) and ((gas with treat\$4) and steel)) and (CVD or "vapor deposition" or "vapour deposition")) and steel) and ((grounded or ground or earthed)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 10:56

-	12	(((((effluent or flue) and ((gas with treat\$4) and steel)) and (wafer or substrate or semiconductor)) and steel) not ((((((effluent or flue) and ((gas with treat\$4) and steel)) and (wafer or substrate or semiconductor)) and steel) and ((grounded or ground or earthed) with steel)) not ((((((effluent or flue) and ((gas with treat\$4) and steel)) and (CVD or "vapor deposition" or "vapour deposition")) and steel) and (grounded or ground or earthed)))) and (static with charge)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 10:57
-	1057	(((((effluent or flue) and ((gas with treat\$4) and steel)) and (wafer or substrate or semiconductor)) and steel) not ((((((effluent or flue) and ((gas with treat\$4) and steel)) and (wafer or substrate or semiconductor)) and steel) and ((grounded or ground or earthed) with steel)) not ((((((effluent or flue) and ((gas with treat\$4) and steel)) and (CVD or "vapor deposition" or "vapour deposition")) and steel) and (grounded or ground or earthed)))) not ((((((effluent or flue) and ((gas with treat\$4) and steel)) and (wafer or substrate or semiconductor)) and steel) not ((((((effluent or flue) and ((gas with treat\$4) and steel)) and (wafer or substrate or semiconductor)) and steel) and ((grounded or ground or earthed) with steel)) not ((((((effluent or flue) and ((gas with treat\$4) and steel)) and (CVD or "vapor deposition" or "vapour deposition")) and steel) and (grounded or ground or earthed)))) and (static with charge))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 10:57
-	24	(((((effluent or flue) and ((gas with treat\$4) and steel)) and (wafer or substrate or semiconductor)) and steel) not ((((((effluent or flue) and ((gas with treat\$4) and steel)) and (wafer or substrate or semiconductor)) and steel) and ((grounded or ground or earthed) with steel)) not ((((((effluent or flue) and ((gas with treat\$4) and steel)) and (CVD or "vapor deposition" or "vapour deposition")) and steel) and (grounded or ground or earthed)))) not ((((((effluent or flue) and ((gas with treat\$4) and steel)) and (wafer or substrate or semiconductor)) and steel) not ((((((effluent or flue) and ((gas with treat\$4) and steel)) and (wafer or substrate or semiconductor)) and steel) and ((grounded or ground or earthed) with steel)) not ((((((effluent or flue) and ((gas with treat\$4) and steel)) and (CVD or "vapor deposition" or "vapour deposition")) and steel) and (grounded or ground or earthed)))) and (static with charge))) and grounding	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 10:58
-	1	(((((effluent or flue) and ((gas with treat\$4) and steel)) and (wafer or substrate or semiconductor)) and steel) not ((((((effluent or flue) and ((gas with treat\$4) and steel)) and (wafer or substrate or semiconductor)) and steel) and ((grounded or ground or earthed) with steel)) not ((((((effluent or flue) and ((gas with treat\$4) and steel)) and (CVD or "vapor deposition" or "vapour deposition")) and steel) and (grounded or ground or earthed)))) not ((((((effluent or flue) and ((gas with treat\$4) and steel)) and (wafer or substrate or semiconductor)) and steel) not ((((((effluent or flue) and ((gas with treat\$4) and steel)) and (wafer or substrate or semiconductor)) and steel) and ((grounded or ground or earthed) with steel)) not ((((((effluent or flue) and ((gas with treat\$4) and steel)) and (CVD or "vapor deposition" or "vapour deposition")) and steel) and (grounded or ground or earthed)))) and (static with charge))) and (grounding with steel)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 11:12
-	1103	((effluent or flue) and ((gas with (treat\$4 or abatement)) and steel)) and (wafer or substrate or semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 11:11
-	1	((effluent or flue) and ((gas with (treat\$4 or abatement)) and steel)) and (wafer or substrate or semiconductor)) and (grounding with steel)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 11:12
-	18	((effluent or flue) and ((gas with (treat\$4 or abatement)) and steel)) and (wafer or substrate or semiconductor)) and (grounded with steel)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/14 11:12
-	1	(US-5955037-\$.did.	USPAT	2004/01/14 13:24